

## ET1840

### End Termination

#### Description

ET1840 is a Pt/Pd/Ag conductor paste. It is a high density, high reliability material, which exhibits high leach resistance, with lower resistivity values. ET1840 is formulated to provide good conductivity while meeting the requirements of solderability, leach resistance, resistance to silver migration and high initial adhesion.

#### Key Features

- Excellent solderability and leach resistance Low resistivity values



*This picture does not show the packaging of ET1840 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

#### Typical Properties

|              |   |
|--------------|---|
| Conductivity | ≤ 35.0 milliohms/square at 9.5 um fired film thickness                          |
| Viscosity    | 300 – 400 Kcps Brookfield HBT SC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C |
| Metal        | AgPdPt  |

#### Recommended Processing Guide

|                           |  |
|---------------------------|--|
| Process Temperature (TDS) | 850 °C peak temperature Dwell time of 8 – 10 minutes at peak |
| Film Thickness            | 11 – 15 µm   |

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